## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

C Matayabas et al.

Title:

POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER

FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Docket No.:

884.946US1

Filed:

June 30, 2003

Examiner:

Howard Weiss

Serial No.: 10/612,328

Due Date: February 10, 2004

Group Art Unit: 2814

## Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.

An Amendment and Response (6 Pages).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10th day of January, 2005.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

**PATENT** 

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: Howard Weiss

al No.:

James C Matayabas et al. 10/612,328

Group Art Unit: 2814

Docket No.: 884.946US1

June 30, 2003

Title:

POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED

SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE

**APPLICATION** 

Assignee:

Intel Corporation

Customer No: 21186

## AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This responds to the Office Action mailed on November 10, 2004. Please amend the above-identified patent application as follows.